

PATENT ASSIGNMENT

Electronic Version v1.1
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| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | |
|---|-----------------------|---------------|----------------|---------------------|------------|---------------|------------|-----------------|------------|---------------------------------|------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tevfik Yucek</td> <td>06/25/2013</td> </tr> <tr> <td>Simone Merlin</td> <td>07/12/2013</td> </tr> <tr> <td>Hemanth Sampath</td> <td>06/30/2013</td> </tr> <tr> <td>Didier Johannes Richard Van Nee</td> <td>08/19/2013</td> </tr> </tbody> </table> | | Name | Execution Date | Tevfik Yucek | 06/25/2013 | Simone Merlin | 07/12/2013 | Hemanth Sampath | 06/30/2013 | Didier Johannes Richard Van Nee | 08/19/2013 |
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| Tevfik Yucek | 06/25/2013 | | | | | | | | | | |
| Simone Merlin | 07/12/2013 | | | | | | | | | | |
| Hemanth Sampath | 06/30/2013 | | | | | | | | | | |
| Didier Johannes Richard Van Nee | 08/19/2013 | | | | | | | | | | |
| RECEIVING PARTY DATA | | | | | | | | | | | |
| Name: | QUALCOMM Incorporated | | | | | | | | | | |
| Street Address: | 5775 Morehouse Drive | | | | | | | | | | |
| City: | San Diego | | | | | | | | | | |
| State/Country: | CALIFORNIA | | | | | | | | | | |
| Postal Code: | 92121 | | | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13901193</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 13901193 | | | | | | |
| Property Type | Number | | | | | | | | | | |
| Application Number: | 13901193 | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | |
| Fax Number: | 5123275575 | | | | | | | | | | |
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| ATTORNEY DOCKET NUMBER: | 123080 | | | | | | | | | | |
| NAME OF SUBMITTER: | Laura Russo | | | | | | | | | | |
| Signature: | /Laura Russo/ | | | | | | | | | | |

CH \$40.00 13901193

PATENT

Date:

08/22/2013

Total Attachments: 12

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ASSIGNMENT

WHEREAS, WE,

1. **Tevfik Yucek**, a citizen of **Turkey**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **Santa Clara, CA**,
2. **Simone Merlin**, a citizen of **Italy**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **San Diego, CA**,
3. **Hemanth Sampath**, a citizen of the **United States of America**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **San Diego, CA**,
4. **Didier Johannes Richard Van Nee**, a citizen of **The Netherlands**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **De Meern, Netherlands**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **INTER-FRAME SPACING DURATION FOR SUB-1 GIGAHERTZ WIRELESS NETWORKS** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **13/901,193** filed **May 23, 2013**, Qualcomm Reference No. **123080**, and all provisional applications relating thereto, together with U.S. Provisional Application No. **61/658,341**, filed **June 11, 2012**, Qualcomm Reference No. **123080P1**, U.S. Provisional Application No. **61/669,489** filed **July 09, 2012**, Qualcomm Reference No. **123080P2** and U.S. Provisional Application No. **61/677,336**, filed on **July 30, 2012**, Qualcomm Reference No. **123080P3** (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the

United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

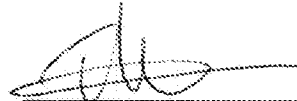
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Jose, on 6/25/2013
LOCATION DATE



Tevfik Yucek

Done at _____, on _____
LOCATION DATE

Simone Merlin

Done at _____, on _____
LOCATION DATE

Hemanth Sampath

Done at _____, on _____
LOCATION DATE

Didier Johannes Richard Van Nee

ASSIGNMENT

WHEREAS, WE,

1. **Tevfik Yucek**, a citizen of **Turkey**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **Santa Clara, CA**,
2. **Simone Merlin**, a citizen of **Italy**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **San Diego, CA**,
3. **Hemanth Sampath**, a citizen of the **United States of America**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **San Diego, CA**,
4. **Didier Johannes Richard Van Nee**, a citizen of **The Netherlands**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **De Meern, Netherlands**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **INTER-FRAME SPACING DURATION FOR SUB-1 GIGAHERTZ WIRELESS NETWORKS** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **13/901,193** filed **May 23, 2013**, Qualcomm Reference No. **123080**, and all provisional applications relating thereto, together with U.S. Provisional Application No. **61/658,341**, filed **June 11, 2012**, Qualcomm Reference No. **123080P1**, U.S. Provisional Application No. **61/669,489** filed **July 09, 2012**, Qualcomm Reference No. **123080P2** and U.S. Provisional Application No. **61/677,336**, filed on **July 30, 2012**, Qualcomm Reference No. **123080P3** (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the

United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
 LOCATION DATE
Tevfik Yucek

Done at San Diego, on 7/12/13
 LOCATION DATE
Simone Merlin
Simone Merlin

Done at _____, on _____
 LOCATION DATE
Hemanth Sampath

Done at _____, on _____
 LOCATION DATE
Didier Johannes Richard Van Nee

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United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

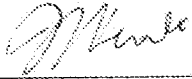
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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Tevfik Yucek

Done at _____, on _____
LOCATION DATE Simone Merlin

Done at San Diego, on 06/30/13
LOCATION DATE 
Hemanth Sampath

Done at _____, on _____
LOCATION DATE Didier Johannes Richard Van Nee

ASSIGNMENT

WHEREAS, WE,

1. **Tevfik Yucek**, a citizen of **Turkey**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121** and a resident of **Santa Clara, CA**,
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WHEREAS, QUALCOMM Incorporated (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

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